

IN THE ABSTRACT

Please substitute the following amended Abstract for the abstract as currently pending. A substitute sheet containing the amended Abstract is also provided.

ABSTRACT OF THE DISCLOSURE

A metal-ceramic circuit board is characterized by being constituted by bonding directly on a base plate of aluminum or aluminum alloy at least one of ceramic substrate boards having a conductive metal member of an electronic circuit. The base plate has a proof stress not higher than 320 (MPa) and a thickness not smaller than 1mm.

REMARKS

By this Amendment, the election made to prosecute the invention of Group I, Claims 1-7, is affirmed. Claims 8-22 are withdrawn as being drawn to a non-elected invention, and Claim 1 has been amended.

In paragraph 5 of the Office Action, the Examiner has objected to the drawings, stating that the cross-hatching of the ceramic (2) in FIGURES 1-5 was not right. Corrected drawings illustrating corrected cross-hatching for the ceramic (2) are submitted herewith.

In paragraph 6 of the Office Action, the Examiner objected to the Abstract. With this Amendment, the abstract and title of the invention are amended.

The Examiner rejected Claims 1-7 under 35 USC sec. 103(a) as being unpatentable over Saitoh (U.S. Pat. No. 6,175,084) in view of Ikeda (U.S. Pat. No. 6,040,039). This rejection is respectfully traversed.

The Examiner states that Saitoh discloses a ceramic substrate board 2. However, the board 2 is not a ceramic substrate. Instead, the board 2 is a first insulating adhesive layer composed of a resin containing at least one of metal oxides and/or at least one of metal nitrides